

7900 Duo Series

Specifications

Machine Model	7900	7900 LA
Workpiece Size	up to 8" X 8"	up to 10" X 10"
Spindle	Two facing spindles 60,000 rpm / 1.2 KW / 0.25 Nm Rated torque	
Blade Size	2" - 3"	
Y1 / Y2 Axis	Ball bearing lead screw Linear encoder 0.1 µm 1.5 µm 1.0 µm	
Drive		
Control		
Resolution		
Cumulative Accuracy		
Indexing Accuracy		
Cutting range	200mm	250mm
X Axis	Air Slide Ball bearing lead screw Up to 600 mm/sec 410 mm	
Drive		
Feed Rate		
Cutting range		
Z1 / Z2 Axis	Ball bearing lead screw Rotary encoder 0.2 µm 1.0 µm 40 mm 2.0 µm	
Drive		
Control		
Resolution		
Repeatability		
Max. stroke		
Accuracy		
Ø Axis	Closed-loop, Direct-drive Linear encoder 4 arc-sec 350°	
Drive		
Control		
Repeatability		
Stroke		
Vision System	High bright LED illumination (vertical and oblique) Continuous Magnification from X70 to X280 or from X35 to X140 (optional)	
Standard Features	Automatic alignment, Automatic Kerf inspection, Automatic Y offset correction	
User Interface	17" Flat screen, Touch screen operation, NUI (New User Interface), Multilanguage support	
Optional	BBD (Broken Blade Detector), High power spindle up to 2.4KW, Barcode reader, Dress station, Geometric Model Finder (GMF), Dicing Floor Management (SECS/GEM)	
Utilities	200-240 VAC, 50/60 Hz, single phase 260 L/min @ 5.5 bar 1.1 L/min Up to 3 L/min	
Electrical		
Air		
Spindle Coolant (per Spindle)		
Cutting water (per Spindle)		
Dimensions	875 x 975 x 1450 mm 900 kg	
WxDxH		
Weight		
Environmental	Typical room temperature: 20°C - 25°C < 70% (relative, non-condensing) Vibration Free	
Temperature		
Humidity		
Floor		

Note: Specifications are subject to change without notice.

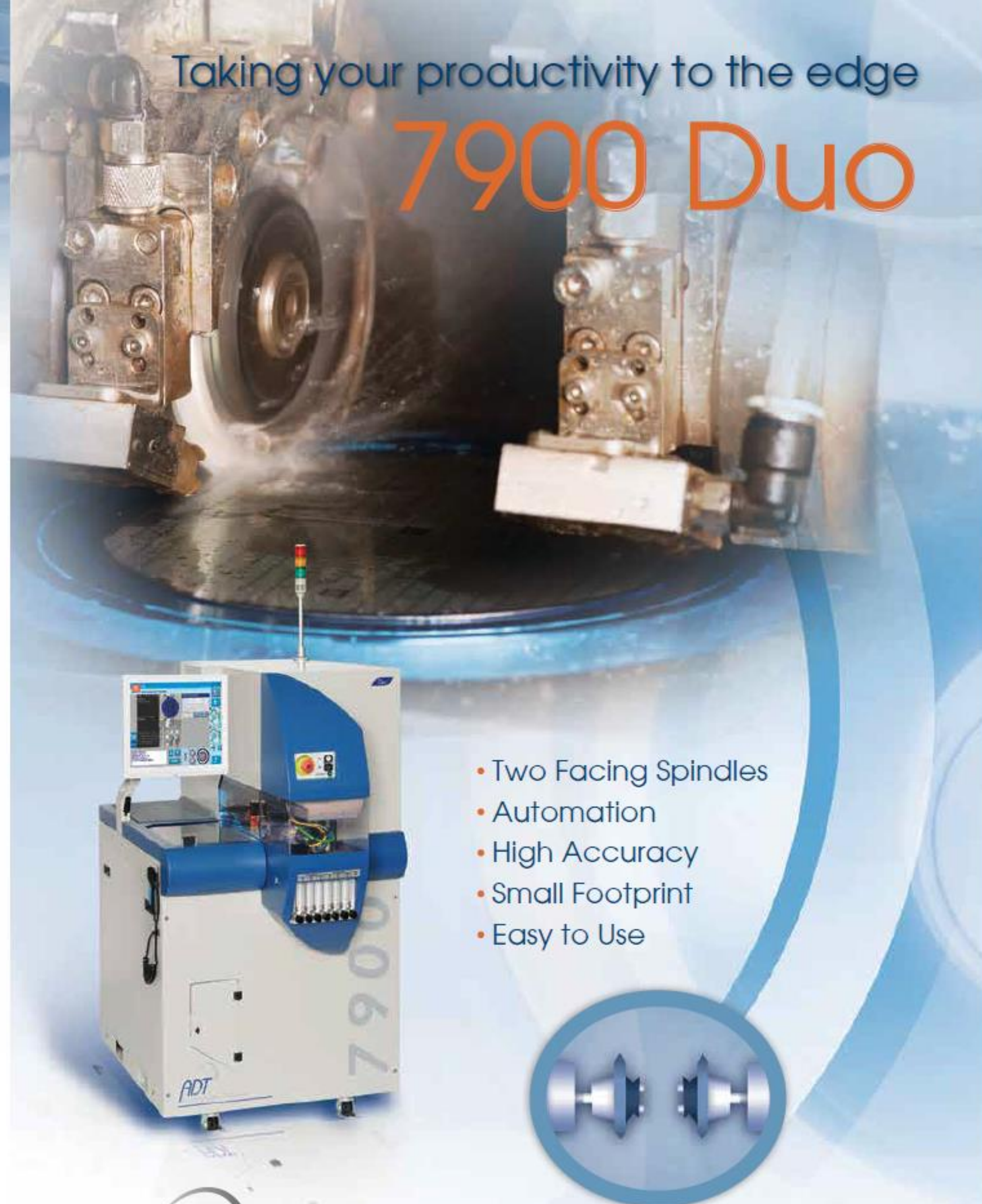


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Taking your productivity to the edge

7900 Duo



- Two Facing Spindles
- Automation
- High Accuracy
- Small Footprint
- Easy to Use

ADT = **Dicing**
Advanced Dicing Technologies

Taking your productivity to the edge

Double your productivity with the 7900 Duo Dicing Saw

Setting new industry standards for productivity, affordability, automation, and ease of use.

Productivity

The 7900 Duo Dicing Saw is configured with two facing spindles that simultaneously dice the wafers, doubling productivity. The dicing saw is fitted with a front mount spindle eliminating the thermal effect that causes cut misplacement, resulting in increased yield.

Affordability

The system's small footprint, combined with high throughput and automation, results in reduced expenses and lowers the cost of ownership (CoO), consequently delivering lower cost per die.

Automation

The powerful automated vision system aligns the wafers and provides Y offset correction and Kerf check to ensure maximum precision.

Ease of Use

The system is equipped with a 17" touch screen and easy to use NUI system for intuitive and efficient programming, set up and operation.

Ideal for LEDs, image sensors, discrete devices, RFIDs, SAW devices, MEMS, and other products that require long cut cycle time.



**x2
UPH**

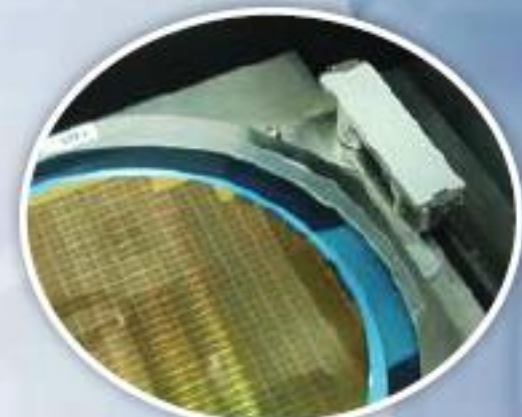
Highly accurate system delivers low cost, high performance

Advantages

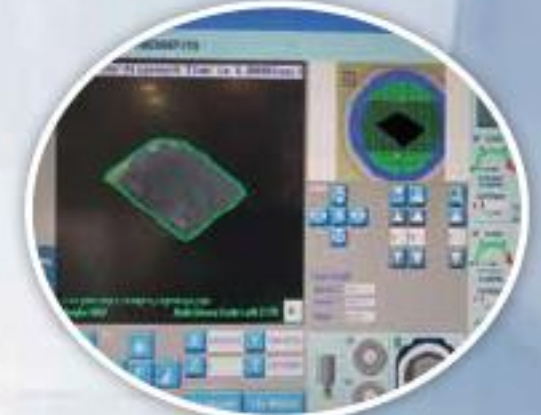
- Two facing spindles enable simultaneous dicing
- Low vibration platform
- Fast automatic alignment and cut positioning increase throughput
- Small footprint reduces cost of ownership
- Automatic Kerf inspection increases yield
- Automatic Y offset correction ensures maximum precision
- Touch screen user interface
- Air bearing feed axis (X)
- Multiple cuts per index

Options

- Advanced multi magnification vision system
- High power spindle for hard and thick applications
- Dressing station
- Geometrical Model Finder (GFM)
- Multi panel support
- Dicing floor management (DFM)
- Shrinkage compensation feature
- Broken wafer recognition
- Tape surface detection
- Customized chucks



Dressing station



Broken wafer recognition

